## **CLAIMS**

## What is claimed is:

- 1 1. An optical modulator device comprising:
- 2 a substrate formed from a semiconductor material;
- an optically active layer formed on an upper surface of the substrate, the optically
- 4 active layer including a layer of SiGe having a quantum well to provide electro-absorption of
- 5 light in the optically active layer;
- a layer of semiconductor material formed on an upper surface of the optically active
- 7 layer; and
- 8 an electrical contact formed on an upper surface of the layer of semiconductor
- 9 material to provide an electric field to alter the electro-absorption of light in the optically
- 10 active layer.
- 1 2. The device of claim 1, wherein the layer of SiGe comprises a layer of SiGe
- 2 nanocrystals.
- 1 3. The device of claim 1, wherein the layer of SiGe is a strained layer of SiGe having a
- 2 dopant to provide electrons in the strained layer of SiGe.
- 1 4. The device of claim 3, wherein the dopant is at least one of arsenic, phosphorus, and
- 2 antimony.
- 1 5. The device of claim 3, wherein the strained layer of SiGe is between 20 and 70
- 2 percent Germanium.
- 1 6. The device of claim 5, wherein the strained layer of SiGe is 27 percent Germanium.

- 1 7. The device of claim 3, wherein the substrate is formed from silicon.
- 1 8. The device of claim 3, further comprising:
- a second layer of semiconductor material formed on an upper surface of the substrate;
- 3 and
- 4 wherein the optically active layer is formed on an upper surface of the second layer of
- 5 semiconductor material.
- 1 9. The device of claim 8, wherein the second layer of semiconductor material is formed
- 2 from silicon.
- 1 10. The device of claim 3, wherein the optically active layer further comprises:
- 2 a layer of semiconductor material formed on an upper surface of the first strained
- 3 layer of SiGe; and
- a second strained layer of SiGe formed on an upper surface of the semiconductor
- 5 layer to provide a second quantum well, wherein the second strained layer of SiGe is doped
- 6 with arsenic.
- 1 11. The device of claim 10, wherein a ratio of silicon to germanium in the first strained
- 2 layer is different than a ratio of silicon to germanium in the second strained layer.
- 1 12. The device of claim 1, wherein the optical modulator is an optical waveguide
- 2 modulator.
- 1 13. The device of claim 12, further comprising an optical cavity in optical
- 2 communication with the optically active layer.

- 1 14. The device of claim 1, wherein the layer of SiGe has a thickness between five and
- 2 thirty nanometers.
- 1 15. The device of claim 1, wherein the substrate is formed from germanium.
- 1 16. An optical modulator device comprising:
- 2 a substrate formed from a semiconductor material;
- a first reflective layer formed on an upper surface of the substrate to provide a first
- 4 reflective surface;
- a first cladding layer formed on an upper surface of the first reflective layer;
- an optically active layer formed on an upper surface of the first cladding layer, the
- 7 optically active layer including a strained layer of SiGe having a quantum well to provide
- 8 electro-absorption of light in the optically active layer;
- a second cladding layer of dielectric material formed on an upper surface of the
- 10 optically active layer; and
- a second reflective layer formed on an upper surface of the second cladding layer to
- 12 provide a second reflective surface.
  - 1 17. The optical modulator device of claim 16, wherein the strained layer of SiGe is doped
  - 2 with arsenic.
  - 1 18. The optical modulator device of claim 17, wherein a concentration of arsenic in the
- 2 strained layer of SiGe is greater than 1 x 10<sup>18</sup> atoms per cubic centimeter.
- 1 19. The optical modulator device of claim 18, wherein a concentration of arsenic in the
- 2 strained layer of SiGe is between  $1 \times 10^{18}$  atoms per cubic centimeter and  $6 \times 10^{20}$  atoms per
- 3 cubic centimeter.

- 1 20. The optical modulator device of claim 16, wherein the strained layer of SiGe is
- 2 between 20 and 70 percent Germanium.
- 1 21. The optical modulator device of claim 16, wherein the substrate is formed from
- 2 silicon.
- 1 22. A method comprising:
- 2 receiving an optical signal at an optical modulator device having an optically active
- 3 layer, the optically active layer including a strained layer of SiGe having a quantum well to
- 4 provide electro-absorption for the received optical signal;
- 5 applying an electric field to the optical modulator device to alter the electro-
- 6 absorption of the optically active layer;
- 7 modulating the received optical signal responsive to the altered electro-absorption of
- 8 the optically active layer; and
- 9 providing the modulated optical signal to an integrated circuit chip.
- 1 23. The method of claim 22, wherein the strained layer of SiGe is doped with arsenic.
- 1 24. The method of claim 23, wherein the strained layer of SiGe is between 20 and 70
- 2 percent Germanium.
- 1 25. A system comprising:
- a first integrated circuit (IC) chip formed from a silicon substrate, the first IC chip
- 3 including an optical modulator with an optically active layer, the optically active layer
- 4 including a strained layer of SiGe having a quantum well to provide electro-absorption of
- 5 light;

- an optical pathway optically coupled at a first optical pathway end to the optical
- 7 modulator; and
- 8 a second IC chip having a photodetector optically coupled to a second optical
- 9 pathway end.
- 1 26. The system of claim 25, wherein the strained layer of SiGe is doped with arsenic.
- 1 27. The system of claim 26, wherein a concentration of arsenic in the strained layer of
- 2 SiGe is greater than 1 x 10<sup>18</sup> atoms per cubic centimeter.
- 1 28. The system of claim 27, wherein a concentration of arsenic in the strained layer of
- 2 SiGe is between  $1 \times 10^{18}$  atoms per cubic centimeter and  $6 \times 10^{20}$  atoms per cubic centimeter.
- 1 29. The system of claim 26, wherein the strained layer of SiGe is between 20 and 70
- 2 percent Germanium.
- 1 30. The system of claim 29, wherein the optically active layer further comprises:
- 2 a second strained layer of SiGe formed on an upper surface of the first strained layer
- 3 of SiGe to provide a second quantum well, wherein the second strained layer of SiGe is
- 4 doped with arsenic.
- 1 31. An integrated circuit comprising:
- a substrate formed from a semiconductor material;
- an optical modulator with an optically active layer formed on the semiconductor
- 4 substrate, the optically active layer including a strained layer of SiGe having a quantum well
- 5 to provide electro-absorption of light; and

- an optical fiber having a first end in optical communication with the optical
- 7 modulator.
- 1 32. The system of claim 31, wherein the strained layer of SiGe is doped with at least one
- 2 of arsenic, phosphorus, and antimony.
- 1 33. The system of claim 32, further comprising a light-emitting source fabricated on the
- 2 semiconductor substrate to provide an optical signal to the optical modulator.
- 1 34. The system of claim 33, further comprising a photodetector in optical communication
- with a second end of the optical fiber to receive light.
- 1 35. The system of claim 31, wherein the substrate is formed from silicon.
- 1 36. The system of claim 35, wherein the strained layer of SiGe is between 20 and 70
- 2 percent Germanium.